



Performance Test Report



AV600-RH-AB

The image shows a large, industrial-grade engine with a prominent cooling fan and various components. The text "AV600-RH-AB" is overlaid in a large, bold, dark blue font.

A vertical collage of three images on the left side of the page: a soldier in a forest, a green geometric pattern, and a military ship at sea.

Product Manager	R&D Leader	Mechanical Engineer	System Engineer	Test Engineer
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Performance Test AV600-RH-AB



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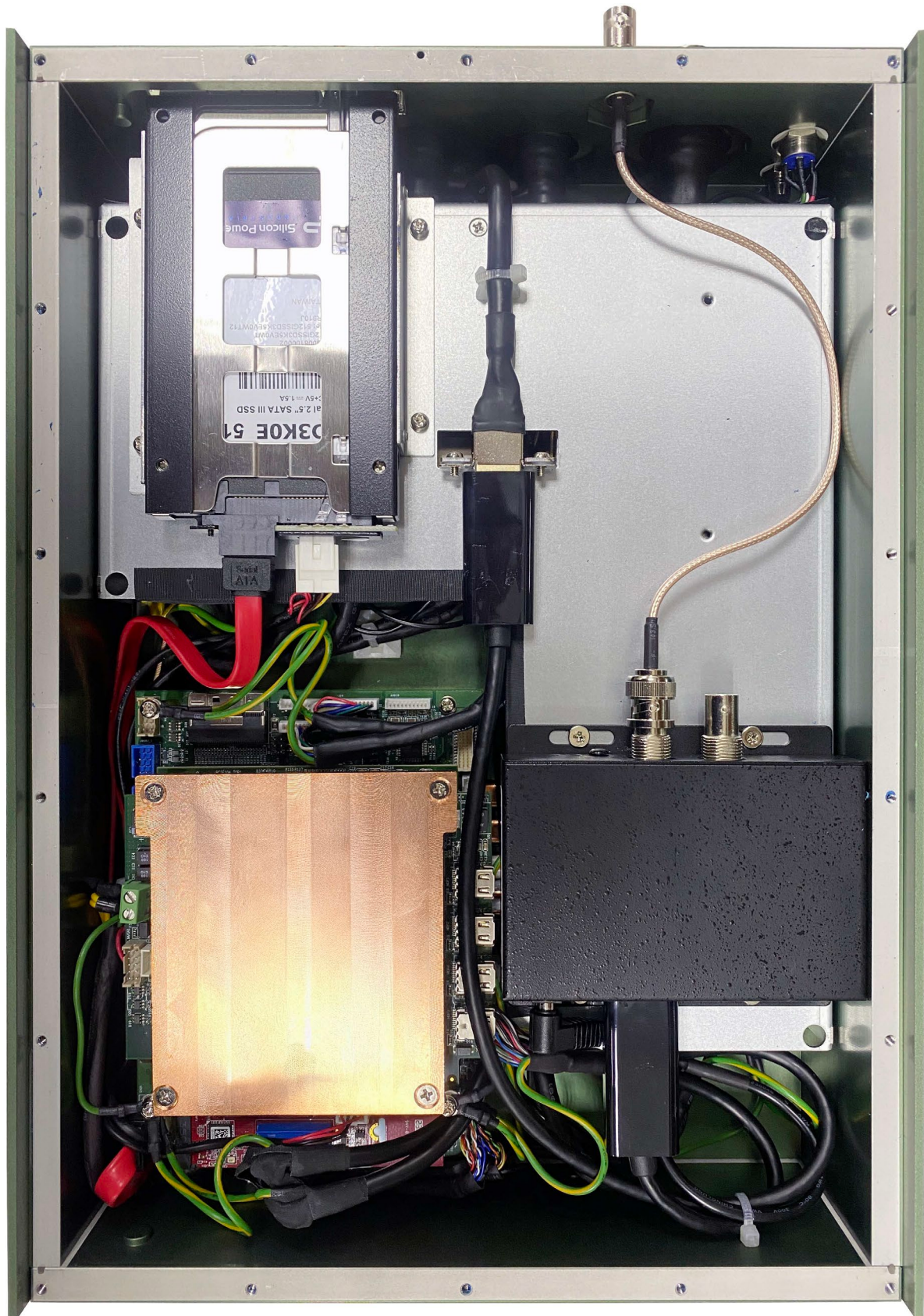
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1. SPECIFICATION

1-1. SYSTEM CONFIGURATION

Motherboard	7Starlake SK516+PCOM-Express Type Basic Size Nodule BIOS Version: 0.0.0 SMBIOS Version: 3.6
CPU	Intel® Core™ i7-13800HRE Processor Total Cores: 14 Performance-cores: 6 Efficient-cores: 8 Total Threads: 20 Performance-core Max Turbo Frequency: 5.00 GHz Efficient-core Max Turbo Frequency: 4.00 GHz Processor Base Frequency: 2.50 GHz Processor Base Power: 45 W Maximum Turbo Power: 115 W
Memory	SAMSUNG 16GB DDR5 SO-DIMM
Storage	SP Industrial 2.5" SATA III SSD 512GB
GPU	NVIDIA RTX A2000 Embedded GPU RAM: 4GB BIOS Version: 94.07.63.00.A2 CUDA Cores: 2560 Base Clock: 607 MHz Boost Clock: 1177 MHz
SDI	SDI Multimedia controller Module

1-2. PRODUCT INTERIOR PHOTOS



2. TEST PLAN

2-1. THERMAL MEASUREMENT PROCESS

Test Purpose	The purpose of performing thermal profile testing is to identify potential thermal issues with the EUT. Considering that semiconductor failure rates rise rapidly with increasing junction temperature, it can aid product reliability assessment. As the system cools down, the mode will change with stack selection, temperature/heat. Mapping can help develop the best tracking arrangements.
Test Equipment	1. KSON THS-B4T-150 Chamber.
Quantity Tested	Minimum 1 Set
Test Software	1. Stress CPU: Passmark BurnInTest _Ver 9.0 2. Stress GPU: AIDA64_Extreme 3. LAN Speed: iPerf3
Test Procedure	1. Thermal pre-scan measurement: Temperature: -20°C ~60°C Humidity: 60%RH 2. Actual thermal measurement: 2-1. Select the test point based on the infrared photo and connect the thermocouple to the hot spot. 2-2. Place the EUT into the hot chamber and set the test temperature curve Specification. 2-3. Open the hot cell and power up the EUT, enter the Windows 10 Pro and perform a maximum power test + stress application. 2-4. After the EUT executes the test software for 8 hours, record the maximum heat generation of each thermocouple point. 2-5. Turn off the hot cell and EUT. 2-6. Verify and check that the recorded information for each component complies with the operating temperature range listed in the specification/approval sheet for each component being tested. 3. For the Operating system software compatibility testing: 3-1.open the thermal chamber and power on the device under test. Enter the Ubuntu 24.02 LTS environment and perform the maximum power test and stress test.
Test Diagram of Curves	Environment defines for 66 hours.

Performance Test

AV600-RH-AB

2-2. TEST RESULT

2-2-1. Temperature Cycle

Aging test of various parts at different temperatures under maximum load and full load conditions.

Test Temperature	Test Result
-20°C	PASS
0°C	PASS
25°C / 60%RH	PASS
40°C / 60%RH	PASS
50°C / 60%RH	PASS
60°C / 60%RH	PASS

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2-2-2. I/O Function

#Confirm the system specifications and I/O connection to ensure that they are functioning properly

Item	Test Criteria	Result
LAN Port (1Gbps)	Connecting to a LAN switch/hub for data transmission test works properly.	PASS
USB Port (USB3.0)	Connect a PassMark USB 3.0 Loopback Plugs for testing, it can work normally.	PASS
USB Port (USB3.0)	Connect a PassMark USB 3.0 Loopback Plugs for testing, it can work normally.	PASS
Serial Port (RS232)	The two devices RS232 are connected to each other, and the data transmission test shows no loss, functioning properly.	PASS
Serial Port (RS232)	The two devices RS232 are connected to each other, and the data transmission test shows no loss, functioning properly.	PASS
DVI	Connecting a DVI monitor displays normally, indicating that the output is functioning properly."	PASS
SDI	After connecting the SDI output to an LCD monitor, the computer display will be mirrored on the screen, indicating that the SDI display function is working properly.	PASS

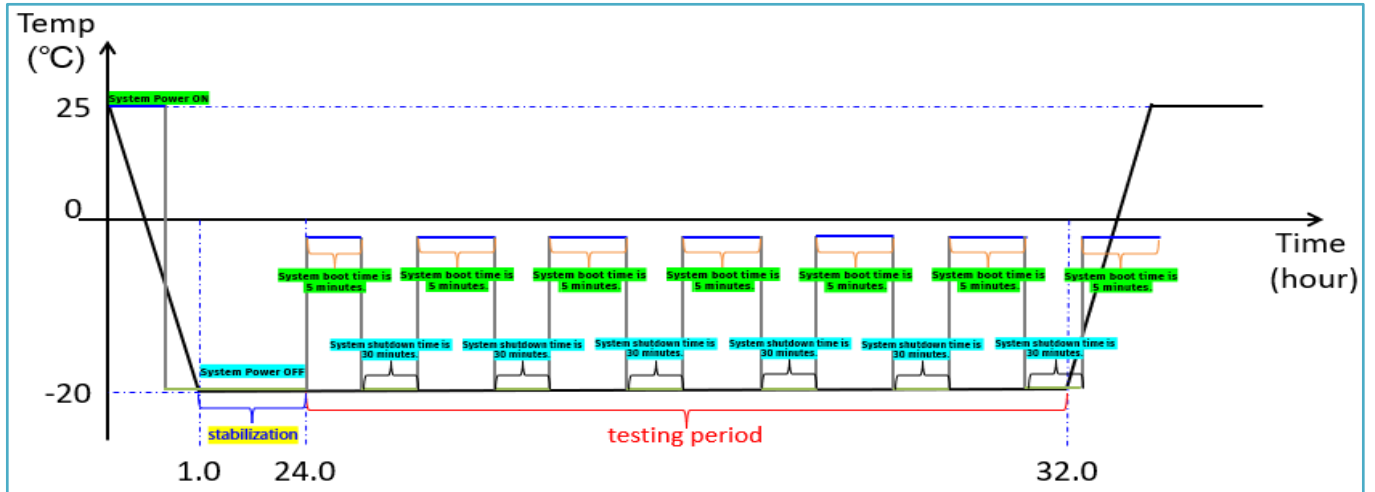
Performance Test

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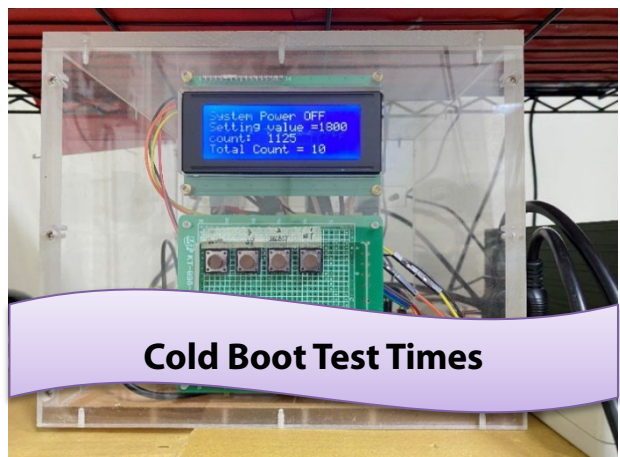
2-2-3. Low-temperature & Boot-up

#Power supply under -20°C and ensure that the system boot up properly

Ambient Temp.	Cold Boot Test Times	Test Result
-20°C	10 times	PASS

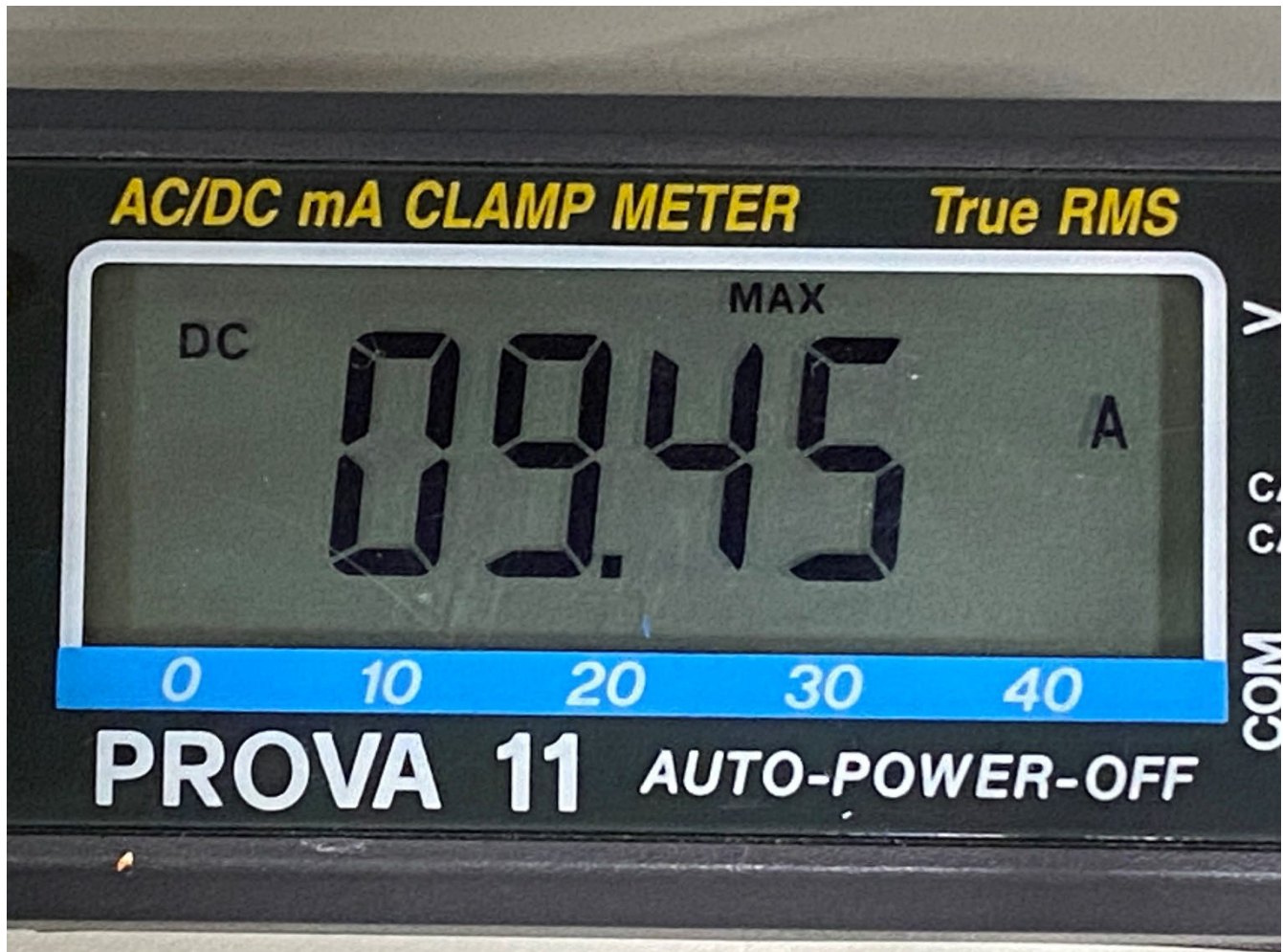


OVERVIEW					
1	-20.5	7	-20.7	13	-0ver
2	-20.9	8	-20.9	14	-0ver
3	-20.6	9	-20.6	15	-0ver
4	-20.8	10	-20.8	16	-0ver
5	-20.6	11	-0ver	17	-0ver
6	-20.5	12	-0ver	18	-0ver



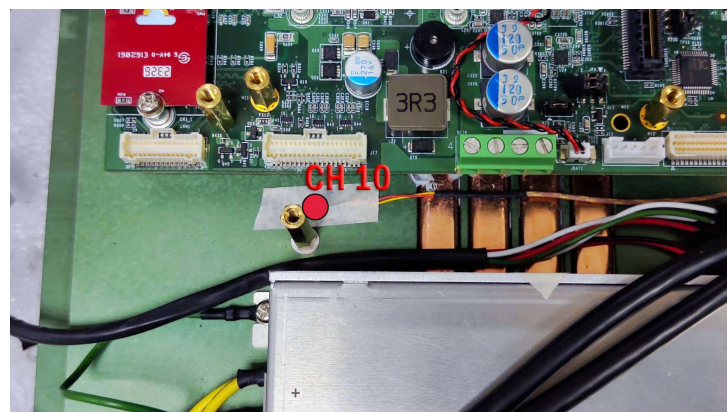
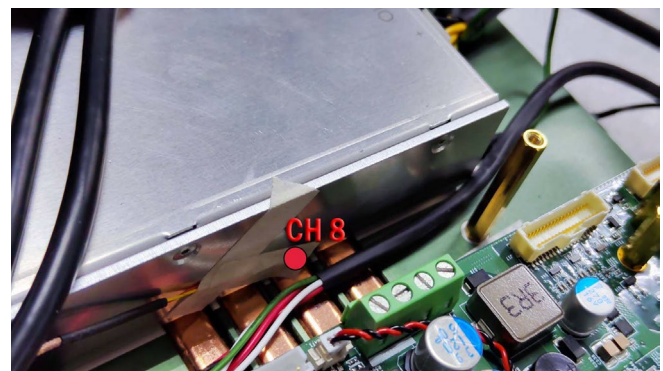
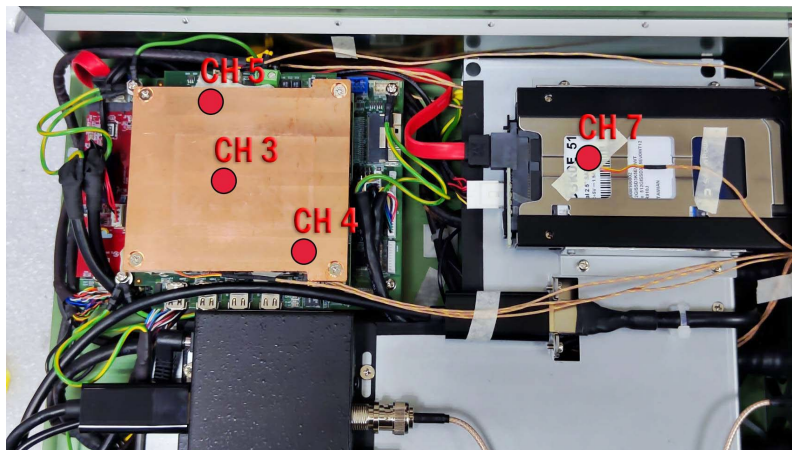
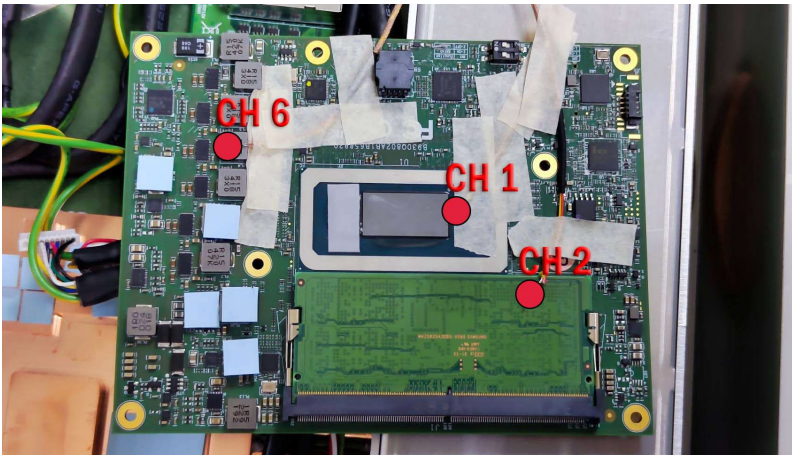
2-3. POWER CONSUMPTION

Voltage	Current	Wattage
24.0V	9.45A	227W



3. TEST PHOTO IN LAB

3-1. Thermocouple Placement

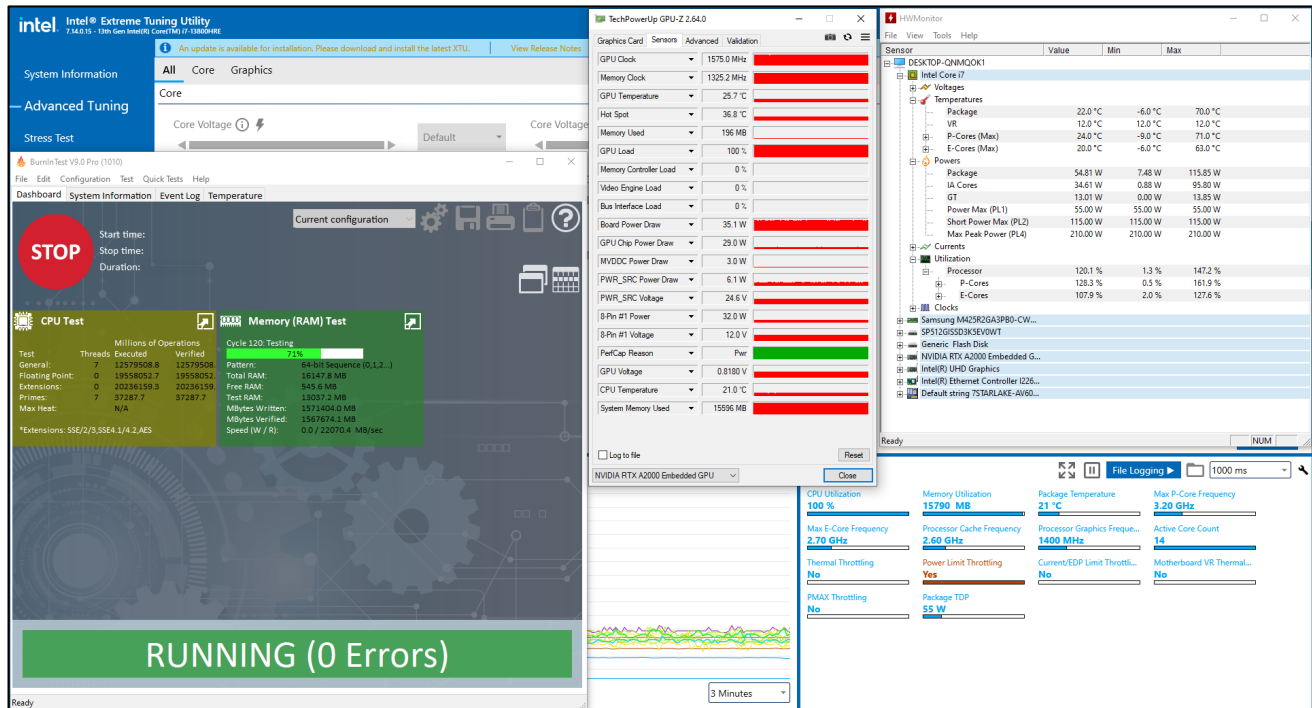


1	CPU	7	SSD
2	DRAM	8	DC-DC Power Board
3	GPU A2000	9	GPU Heatsink
4	GPU DRAM	10	TOP Heatsink
5	GPU MOSFET	11	
6	PL4 MOSFET	12	

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3-2. ENVIRONMENTAL TEMPERATURE TEST

- Chamber in -20°C



OVERVIEW				
1hour				
1	-1.1	-6.0	-0ver	-0ver
2	-6.4	-10.1	-0ver	-0ver
3	22.5	10.9	-0ver	-0ver
4	15.8	-4.1	-0ver	-0ver
5	14.7	-0ver	-0ver	-0ver
6	-6.9	-0ver	-0ver	-0ver

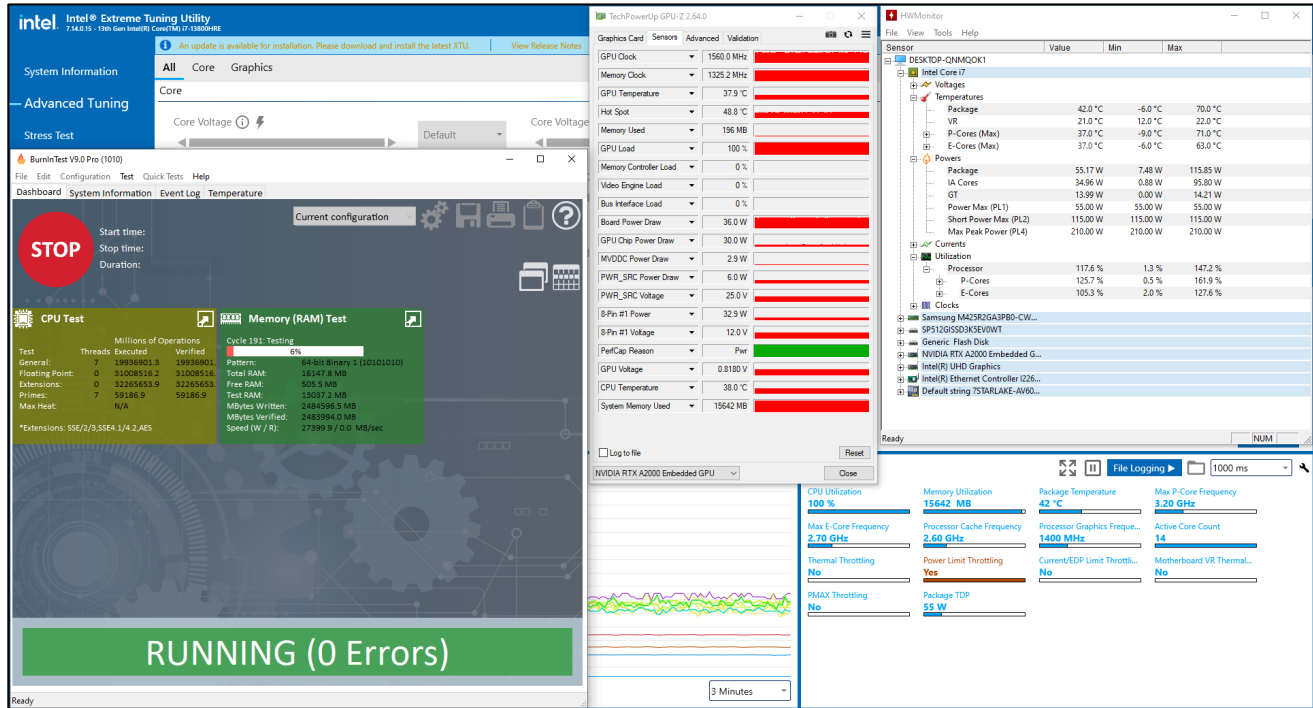
Measuring Point	Ambient Temp.	-20°C
	CPU P-Cores Max Temperature	24.0 °C
	CPU E-Cores Max Temperature	20.0 °C
	CPU P-Cores Frequency	3.20 GHz
	CPU E-Cores Frequency	2.70 GHz
	GPU Temperature	25.7 °C
	GPU Hot Spot Temperature	36.8 °C
	GPU Frequency	1575.0 MHz
CH1	CPU	-1.1 °C
CH2	DRAM	-6.4 °C
CH3	GPU A2000	22.5 °C
CH4	GPU DRAM	15.8 °C
CH5	GPU MOSFET	14.7 °C
CH6	PL4 MOSFET	-6.9 °C
CH7	2.5" SSD	-6.0 °C
CH8	DC-DC Power Module	-10.1 °C
CH9	GPU Heat sink	10.9 °C
CH10	TOP Heat sink	-4.1 °C



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- Chamber in 0°C



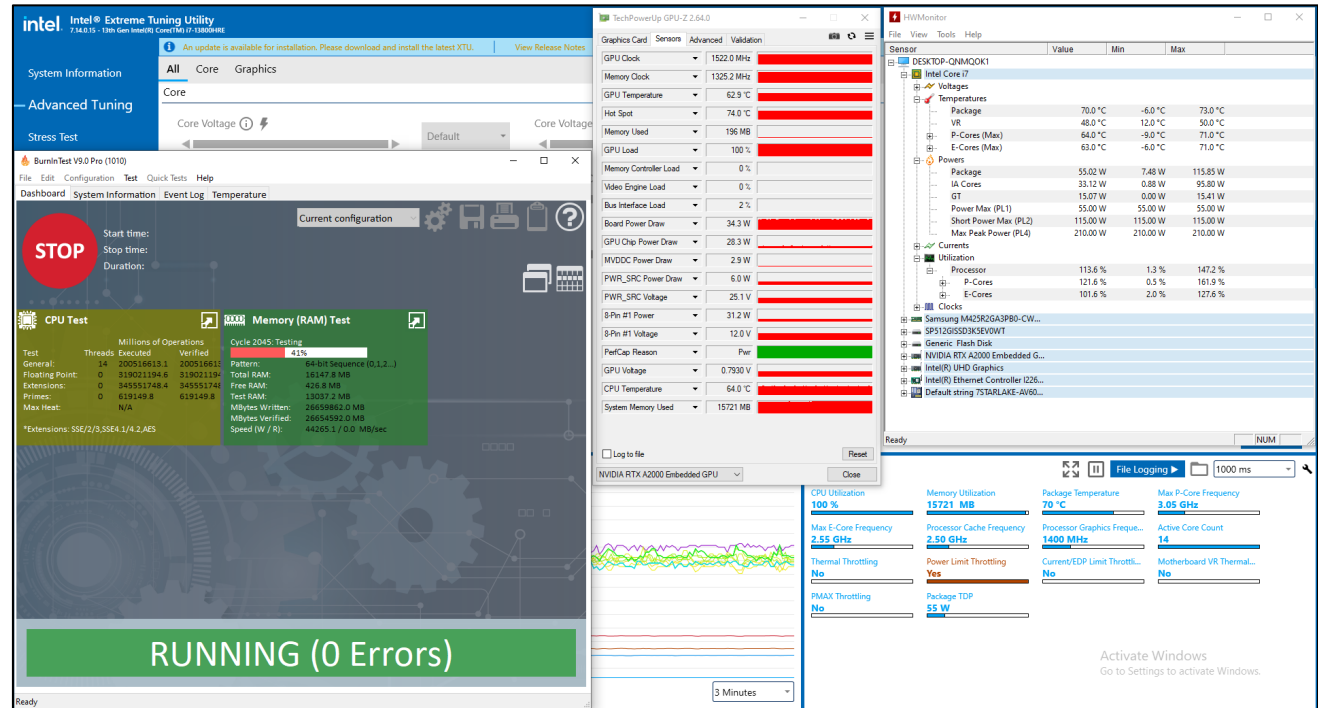
OVERVIEW					
2025/03/04 17:51:15					
1	7	13	19	-Over	-Over
2	8	14	20	-Over	-Over
3	9	15	21	-Over	-Over
4	10	16	22	-Over	-Over
5	11	17	23	-Over	-Over
6	12	18	24	-Over	-Over

Measuring Point	Ambient Temp.	0°C
CPU P-Cores Max Temperature		37.0 °C
CPU E-Cores Max Temperature		37.0 °C
CPU P-Cores Frequency		3.20 GHz
CPU E-Cores Frequency		2.70 GHz
GPU Temperature		37.9 °C
GPU Hot Spot Temperature		48.8 °C
GPU Frequency		1560.0 MHz
CH1	CPU	15.3 °C
CH2	DRAM	10.0 °C
CH3	GPU A2000	35.9 °C
CH4	GPU DRAM	29.1 °C
CH5	GPU MOSFET	28.4 °C
CH6	PL4 MOSFET	8.5 °C
CH7	2.5" SSD	10.9 °C
CH8	DC-DC Power Module	9.8 °C
CH9	GPU Heat sink	25.0 °C
CH10	TOP Heat sink	13.5 °C



Performance Test AV600-RH-AB

- Chamber in 25°C



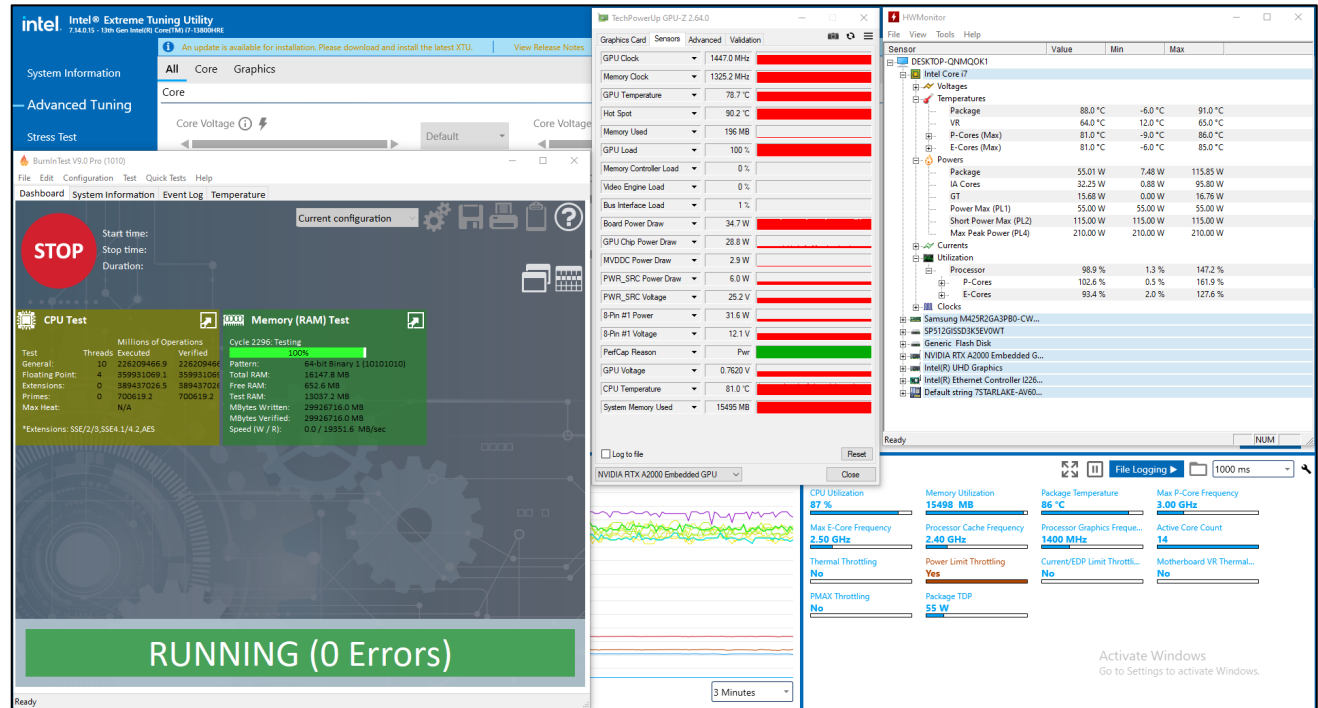
OVERVIEW				
1	7	13	19	
41.7	37.4	-0ver	-0ver	
2	8	14	20	
37.5	36.9	-0ver	-0ver	
3	9	15	21	
61.1	50.6	-0ver	-0ver	
4	10	16	22	
54.3	40.1	-0ver	-0ver	
5	11	17	23	
53.6	-0ver	-0ver	-0ver	
6	12	18	24	
39.5	-0ver	-0ver	-0ver	

Measuring Point	Ambient Temp.	25°C
CPU P-Cores Max Temperature		64.0 °C
CPU E-Cores Max Temperature		63.0 °C
CPU P-Cores Frequency		3.05 GHz
CPU E-Cores Frequency		2.55 GHz
GPU Temperature		62.9 °C
GPU Hot Spot Temperature		74.0 °C
GPU Frequency		1522.0 MHz
CH1	CPU	41.7 °C
CH2	DRAM	37.5 °C
CH3	GPU A2000	61.1 °C
CH4	GPU DRAM	54.3 °C
CH5	GPU MOSFET	53.6 °C
CH6	PL4 MOSFET	39.5 °C
CH7	2.5" SSD	37.4 °C
CH8	DC-DC Power Module	40.1 °C
CH9	GPU Heat sink	50.6 °C
CH10	TOP Heat sink	41.7 °C



Performance Test AV600-RH-AB

- Chamber in 40°C



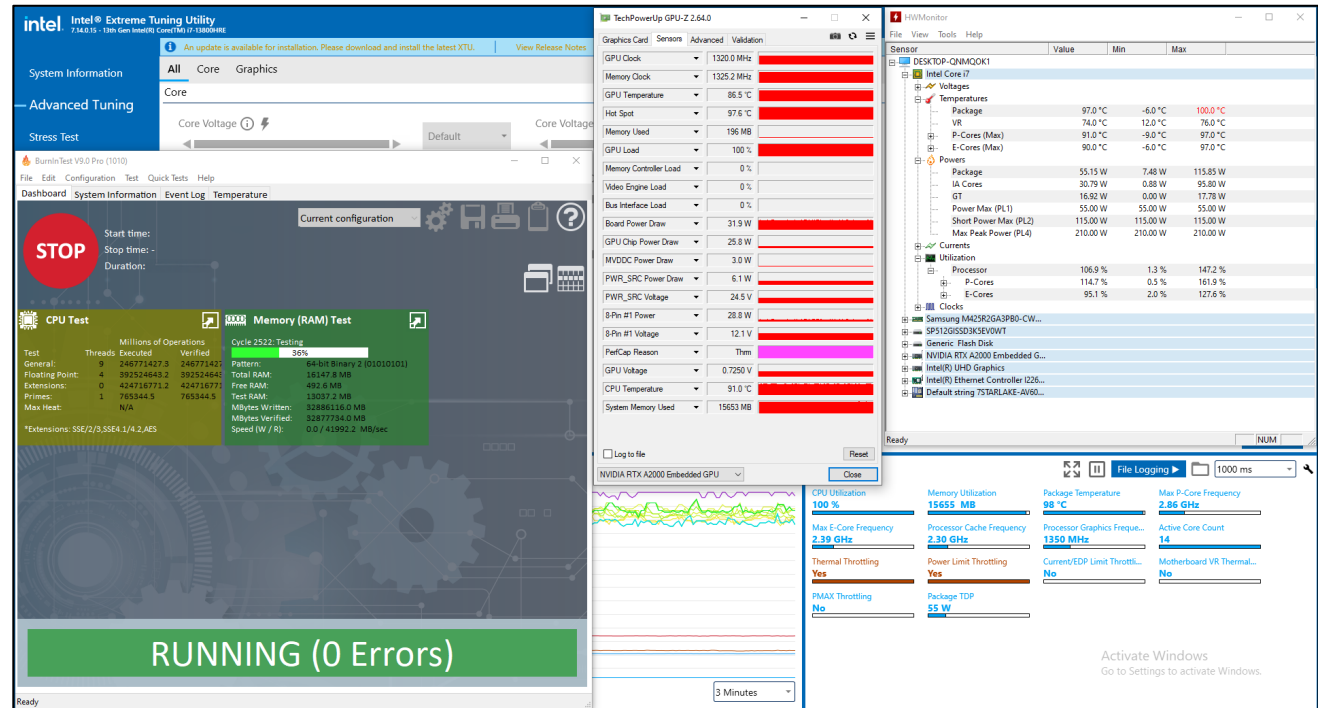
OVERVIEW				
1	7	13	19	
56.8	52.1	-Over	-Over	
2	8	14	20	
52.6	51.5	-Over	-Over	
3	9	15	21	
76.2	65.5	-Over	-Over	
4	10	16	22	
69.1	54.9	-Over	-Over	
5	11	17	23	
68.2	-Over	-Over	-Over	
6	12	18	24	
54.2	-Over	-Over	-Over	

Measuring Point	Ambient Temp.	40°C
	CPU P-Cores Max Temperature	81.0 °C
	CPU E-Cores Max Temperature	81.0 °C
	CPU P-Cores Frequency	3.00 GHz
	CPU E-Cores Frequency	2.50 GHz
	GPU Temperature	78.7 °C
	GPU Hot Spot Temperature	90.2 °C
	GPU Frequency	1447.0 MHz
CH1	CPU	56.8 °C
CH2	DRAM	52.6 °C
CH3	GPU A2000	76.2 °C
CH4	GPU DRAM	69.1 °C
CH5	GPU MOSFET	68.2 °C
CH6	PL4 MOSFET	54.2 °C
CH7	2.5" SSD	52.1 °C
CH8	DC-DC Power Module	51.6 °C
CH9	GPU Heat sink	65.5 °C
CH10	TOP Heat sink	54.9 °C



Performance Test AV600-RH-AB

- Chamber in 50°C



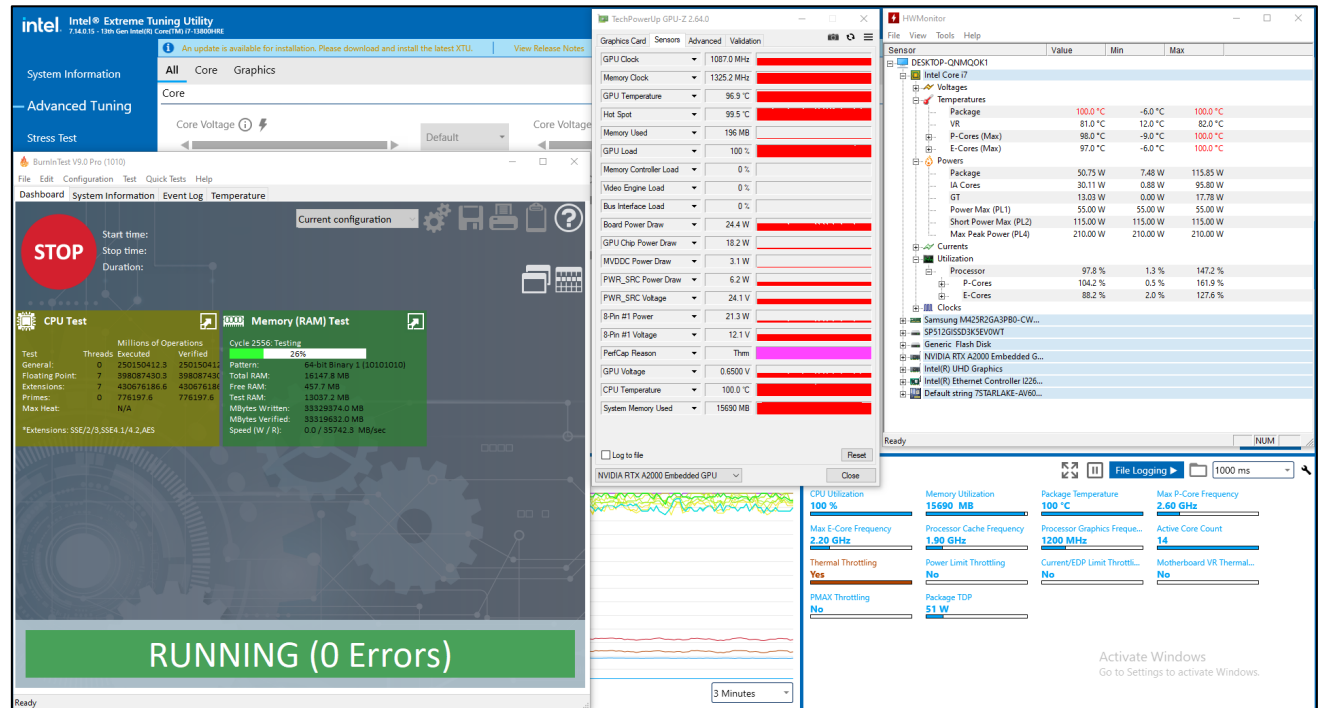
OVERVIEW				
STOP EVENT 1hour				
1	66.9	62.3	13	-Over
2	62.6	61.6	14	-Over
3	84.3	74.4	15	-Over
4	78.0	64.7	16	-Over
5	77.0	-Over	17	-Over
6	63.9	-Over	18	-Over
			19	-Over
			20	-Over
			21	-Over
			22	-Over
			23	-Over
			24	-Over

Measuring Point	Ambient Temp.	50°C
	CPU P-Cores Max Temperature	91.0 °C
	CPU E-Cores Max Temperature	90.0 °C
	CPU P-Cores Frequency	2.86 GHz
	CPU E-Cores Frequency	2.39 GHz
	GPU Temperature	86.5 °C
	GPU Hot Spot Temperature	97.6 °C
	GPU Frequency	1320.0 MHz
CH1	CPU	66.9 °C
CH2	DRAM	62.6 °C
CH3	GPU A2000	84.3 °C
CH4	GPU DRAM	78.0 °C
CH5	GPU MOSFET	77.0 °C
CH6	PL4 MOSFET	63.9 °C
CH7	2.5" SSD	62.3 °C
CH8	DC-DC Power Module	61.6 °C
CH9	GPU Heat sink	74.4 °C
CH10	TOP Heat sink	64.7 °C



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- Chamber in 60°C



OVERVIEW				
1	75.4	71.1	13	19
2	71.5	70.3	14	20
3	85.8	78.8	15	21
4	81.5	72.7	16	22
5	80.9	-Over	17	23
6	72.1	-Over	18	24

Measuring Point	Ambient Temp.	60°C
	CPU P-Cores Max Temperature	98.0 °C
	CPU E-Cores Max Temperature	97.0 °C
	CPU P-Cores Frequency	2.60 GHz
	CPU E-Cores Frequency	2.20 GHz
	GPU Temperature	96.9 °C
	GPU Hot Spot Temperature	99.5 °C
	GPU Frequency	1087.0 MHz
CH1	CPU	75.4 °C
CH2	DRAM	71.1 °C
CH3	GPU A2000	85.8 °C
CH4	GPU DRAM	81.5 °C
CH5	GPU MOSFET	80.9 °C
CH6	PL4 MOSFET	72.1 °C
CH7	2.5" SSD	71.1 °C
CH8	DC-DC Power Module	70.3 °C
CH9	GPU Heat sink	78.8 °C
CH10	TOP Heat sink	72.7 °C



4. THERMAL TEST RESULT(-20°C ~ +60°C)

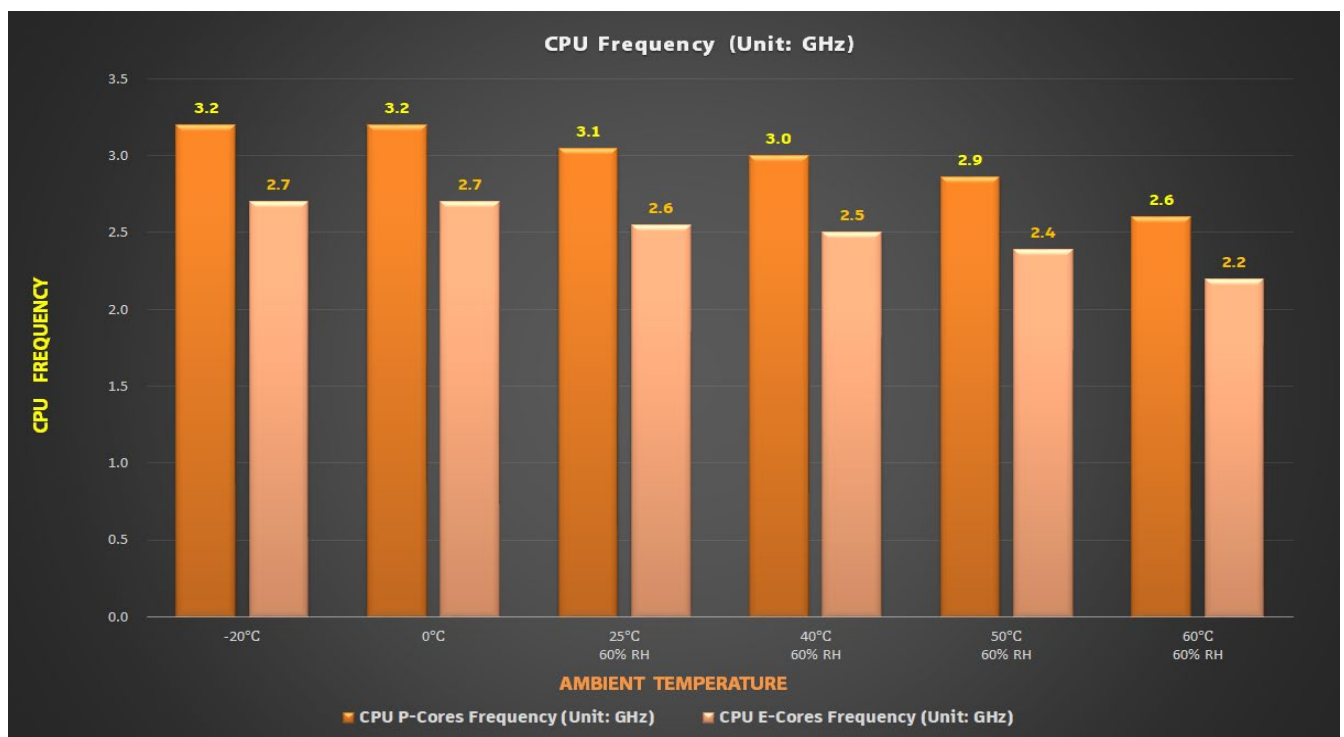
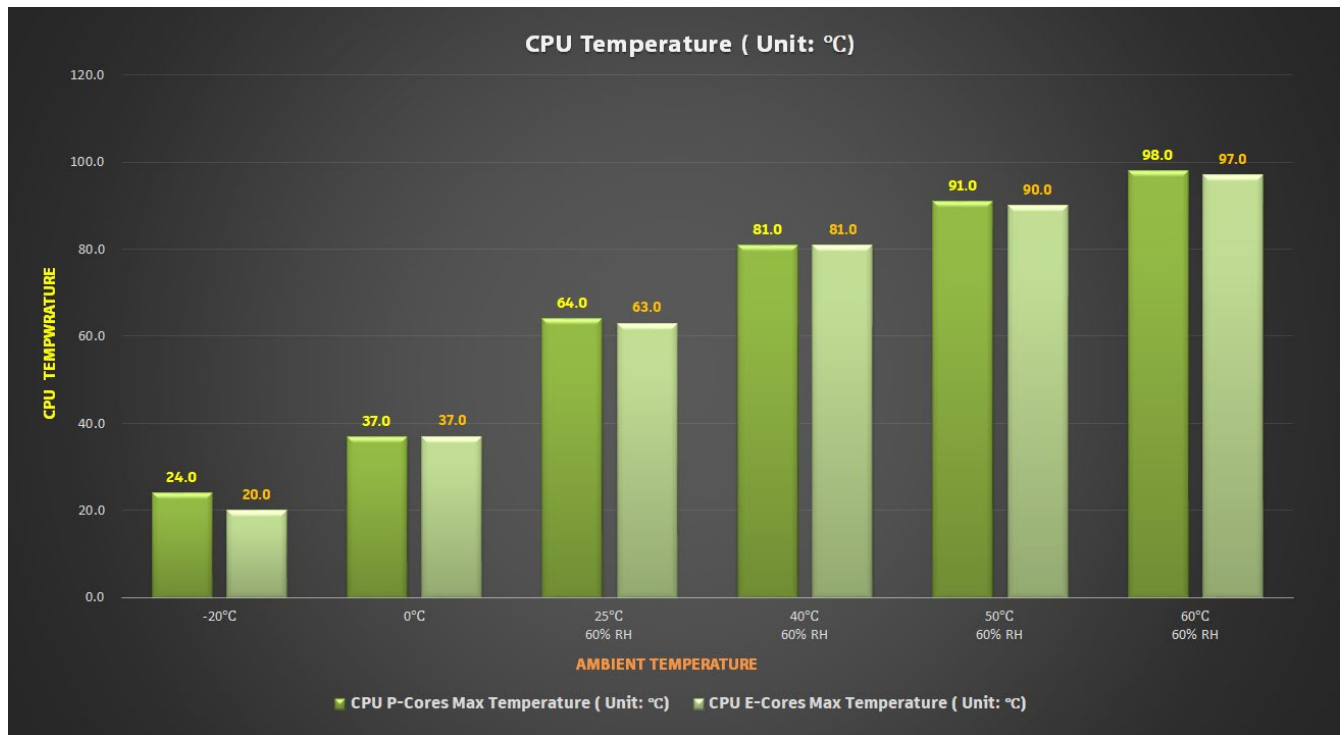
Temperature / Ambient Temp.		-20°C	0°C	25°C 60% RH	40°C 60% RH	50°C 60% RH	60°C 60% RH
Frequency							
CPU P-Cores Max Temperature (Unit: °C)		24.0	37.0	64.0	81.0	91.0	98.0
CPU E-Cores Max Temperature (Unit: °C)		20.0	37.0	63.0	81.0	90.0	97.0
CPU P-Cores Frequency (Unit: GHz) Processor Base Frequency:2.5 GHz		3.20	3.20	3.05	3.00	2.86	2.60
CPU E-Cores Frequency (Unit: GHz)		2.70	2.70	2.55	2.50	2.39	2.20

Temperature / Ambient Temp.		-20°C	0°C	25°C 60% RH	40°C 60% RH	50°C 60% RH	60°C 60% RH
Frequency							
GPU Temperature (Unit: °C)		25.7	37.9	62.9	78.7	86.5	96.9
GPU Hot Spot Temperature (Unit: °C)		36.8	48.8	74.0	90.2	97.6	99.5
GPU Frequency (Unit: MHz)		1575.0	1560.0	1522.0	1447.0	1320.0	1087.0

Thermocouple / Ambient Temp.		-20°C	0°C	25°C 60% RH	40°C 60% RH	50°C 60% RH	60°C 60% RH
measuring point							
CH1	CPU	-1.1	15.3	41.7	56.8	66.9	75.4
CH2	DRAM	-6.4	10.0	37.5	52.6	62.6	71.5
CH3	GPU A2000	22.5	35.9	61.1	76.2	84.3	85.8
CH4	GPU DRAM	15.8	29.1	54.3	69.1	78.0	81.5
CH5	GPU MOSFET	14.7	28.4	53.6	68.2	77.0	80.9
CH6	PL4 MOSFET	-6.9	8.5	39.5	54.2	63.9	72.1
CH7	2.5" SSD	-6.0	10.9	37.4	52.1	62.3	71.1
CH8	DC-DC Power Module	-10.1	9.8	36.9	51.6	61.6	70.3
CH9	GPU Heat sink	10.9	25.0	50.6	65.5	74.4	78.8
CH10	TOP Heat sink	-4.1	13.5	40.1	54.9	64.7	72.7

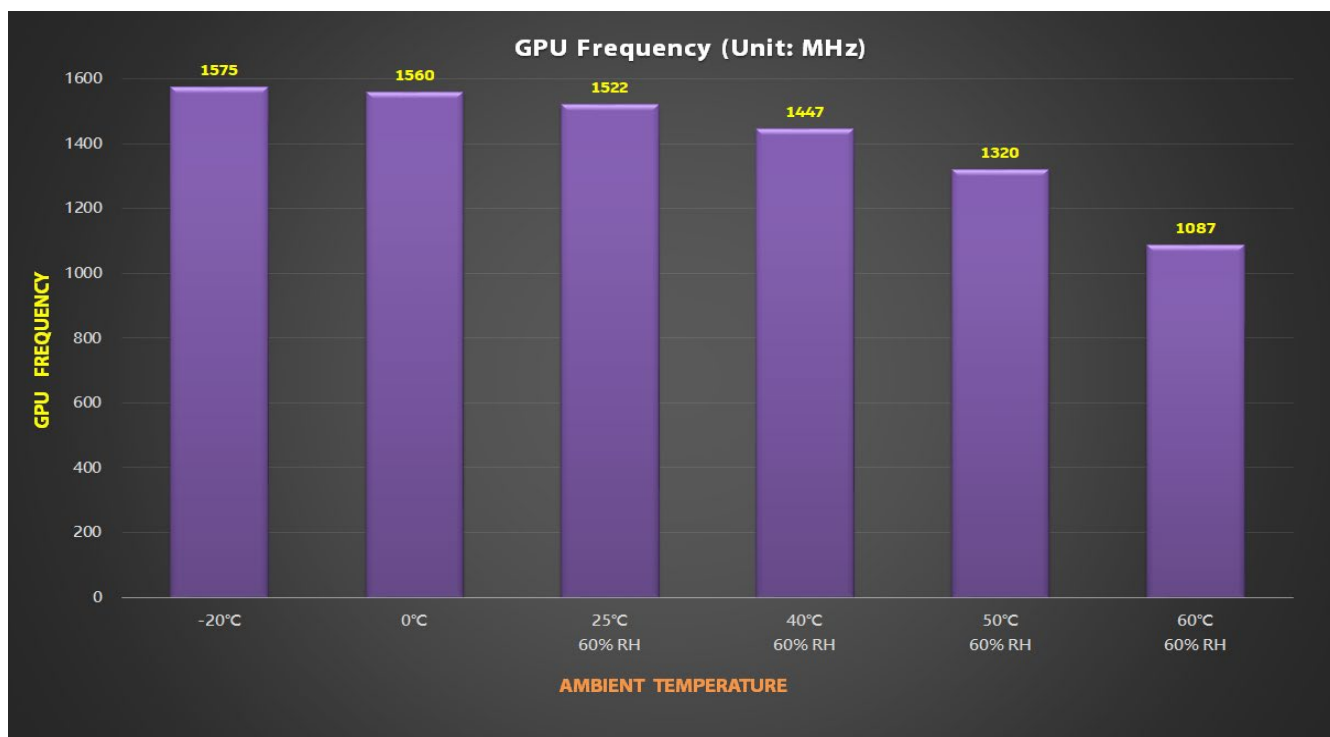
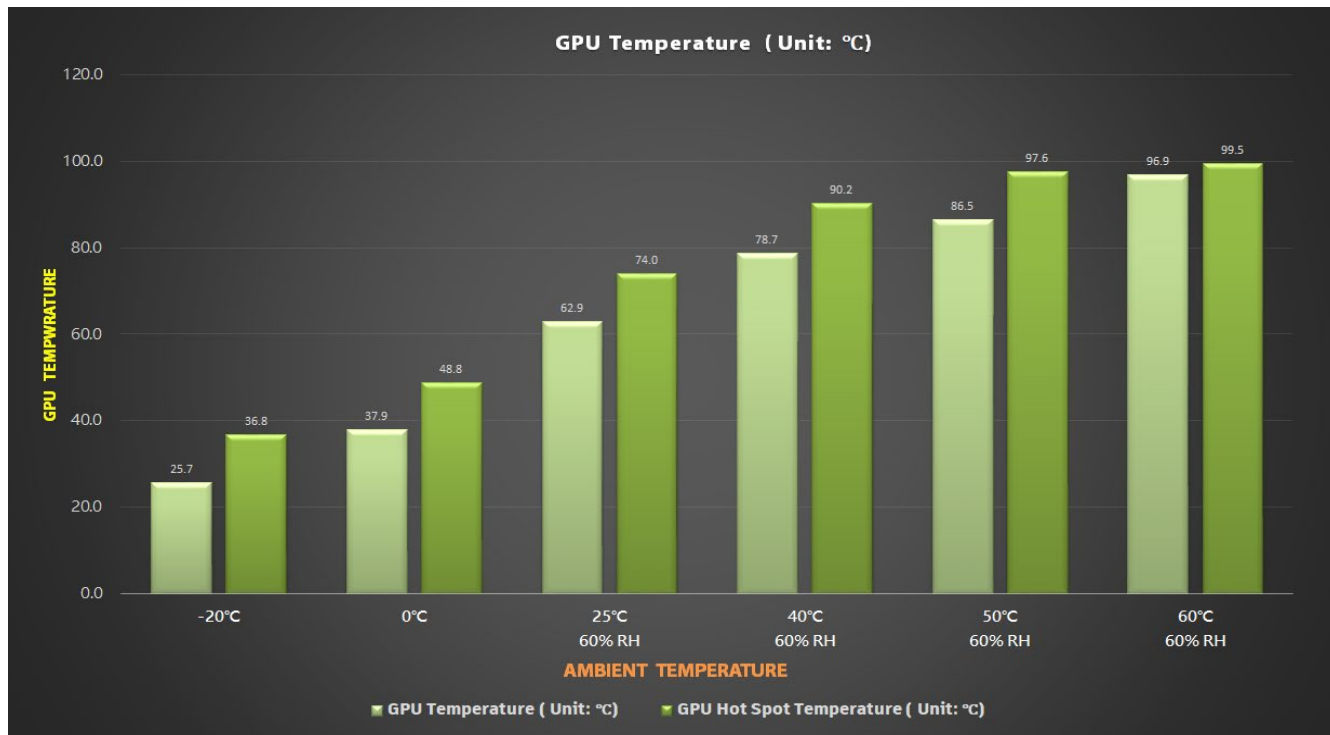
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5. I/O FUNCTION TEST

5-1. USB 3.0



PassMark(TM) USB3Test

Select USB Device

Device: PMU33ZQ2CX (SuperSpeed 5Gb/s)

Connection Type: SuperSpeed 5Gb/s

Test mode

☐ Loopback

☒ Benchmark

X2_USB3.0

Results Status: BENCHMARK test - Complete

Duration: 000h 30m 00s Operations: 0 Errors: 0

Write block 2382: 3370.7 Mb/s (421.3 MB/s)
Read block 2383: 3371.7 Mb/s (421.5 MB/s)
Write block 2383: 3371.0 Mb/s (421.4 MB/s)
Read block 2384: 3368.2 Mb/s (421.0 MB/s)
Write block 2384: 3371.4 Mb/s (421.4 MB/s)
Read block 2385: 3369.4 Mb/s (421.2 MB/s)
Write block 2385: 3092.7 Mb/s (386.6 MB/s)
Read block 2386: 3371.0 Mb/s (421.4 MB/s)
OVERALL BENCHMARK RESULT:
Test Start time:
Duration: 000h 30m 00s
Total number of bytes written: 304087 MB
Total number of bytes read: 304215 MB
Maximum Write Data Rate: 3372.1 Mb/s (421.5 MB/s)
Maximum Read Data Rate: 3372.5 Mb/s (421.6 MB/s)
Minimum Write Data Rate: 2726.0 Mb/s (340.8 MB/s)
Minimum Read Data Rate: 2720.0 Mb/s (340.0 MB/s)
Average Write Data Rate: 3350.0 Mb/s (418.8 MB/s)
Average Read Data Rate: 3361.8 Mb/s (420.2 MB/s)
Average Data Rate: 3355.9 Mb/s (419.5 MB/s)
Minimum Data Rate: 2720.0 Mb/s (340.0 MB/s)

Max. Rate 3372

4000

3000

2000

1000

0 (Mb/s)

R/W

Voltage 4.98V

Speed 5Gb/s

Duration 30 Minutes

Start Stop

Configure Flash LEDs

Clear Serial Save Log

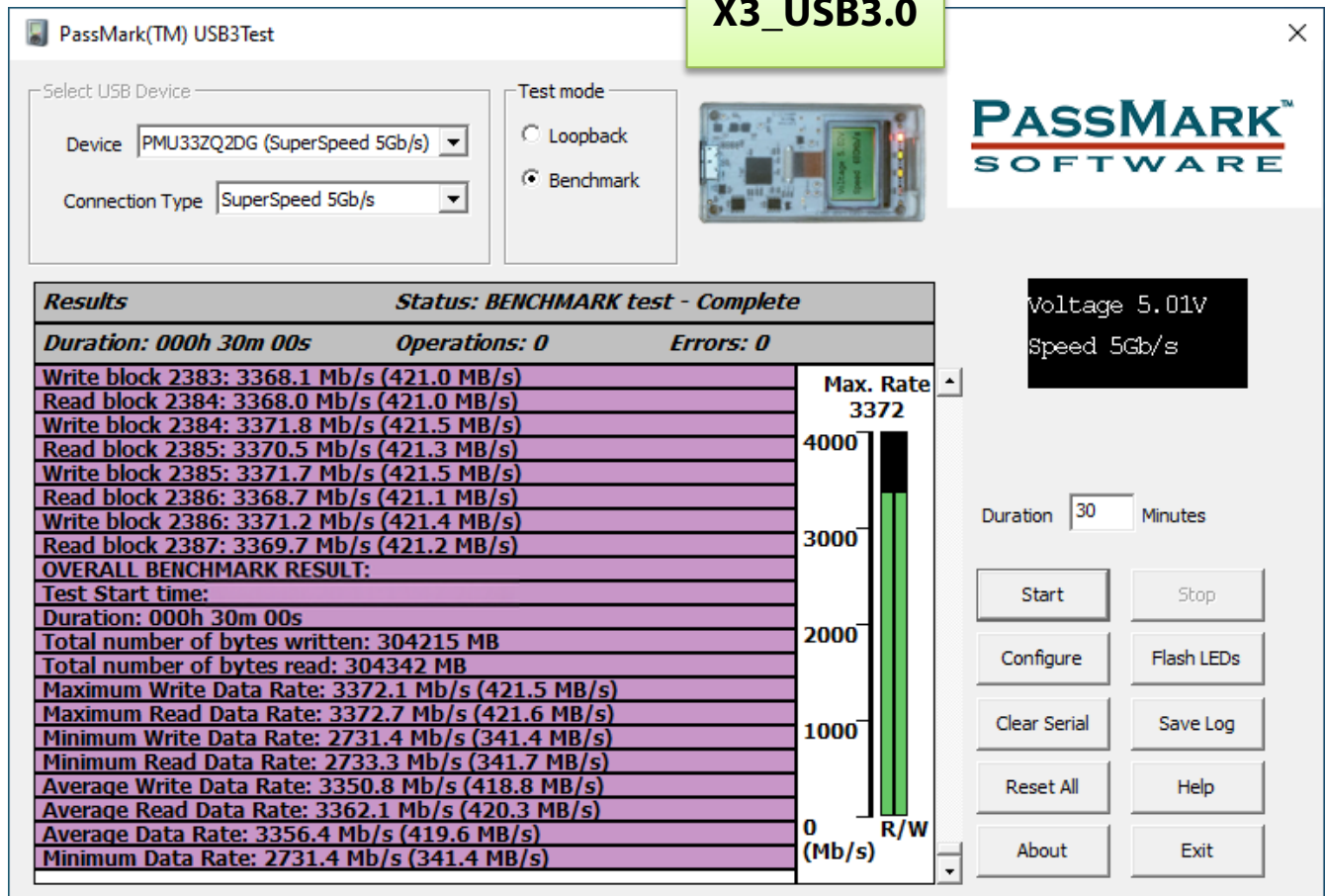
Reset All Help

About Exit

Performance Test

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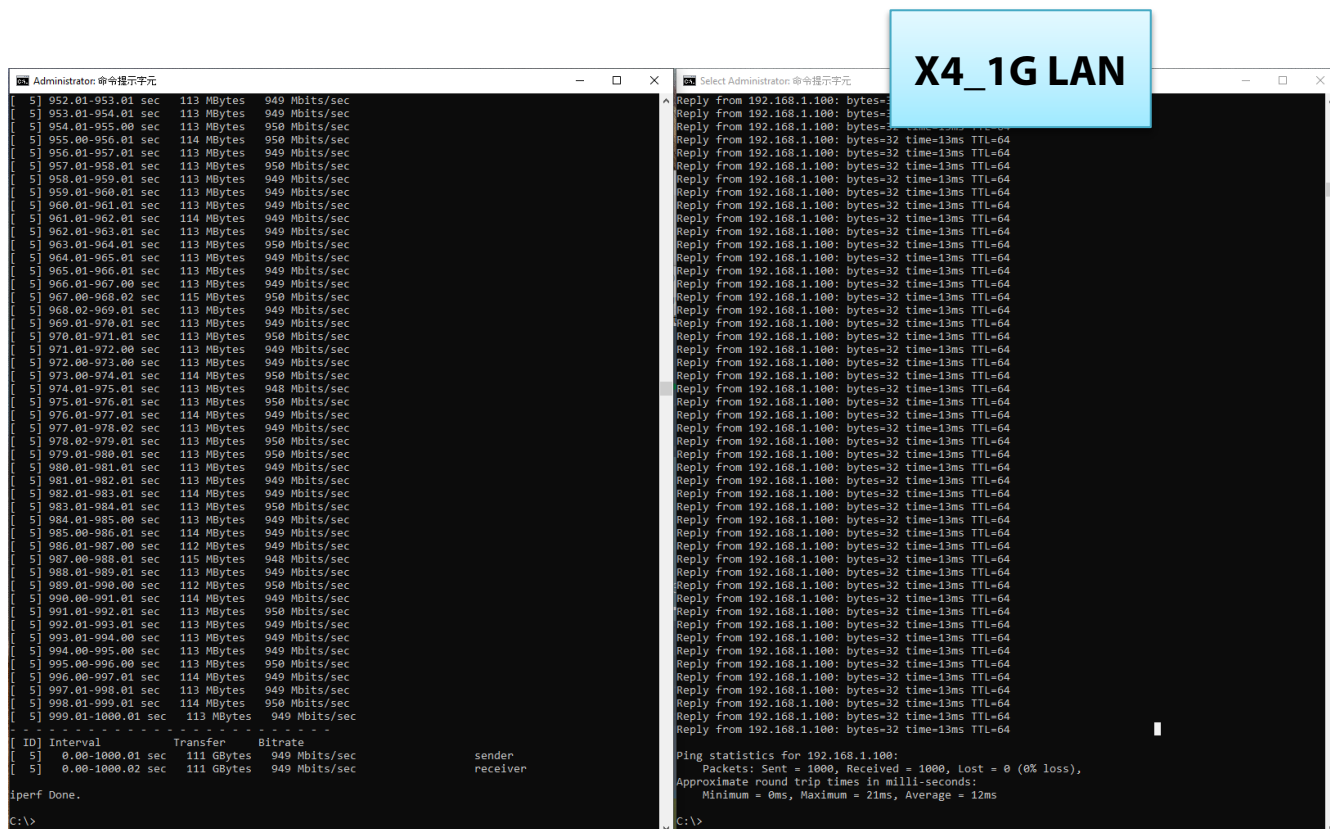
X3_USB3.0



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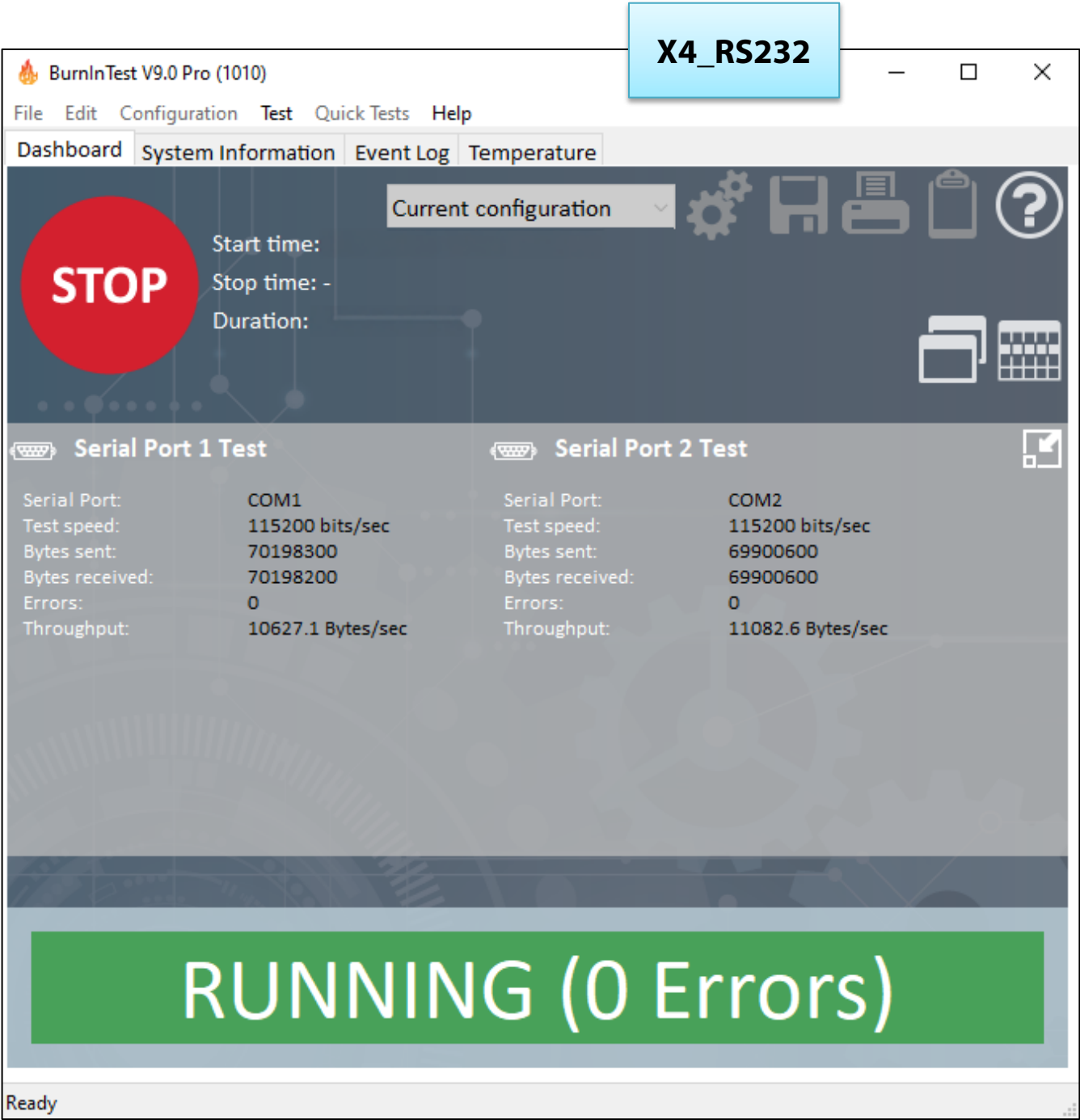
5-2. 1GbE LAN & RS232



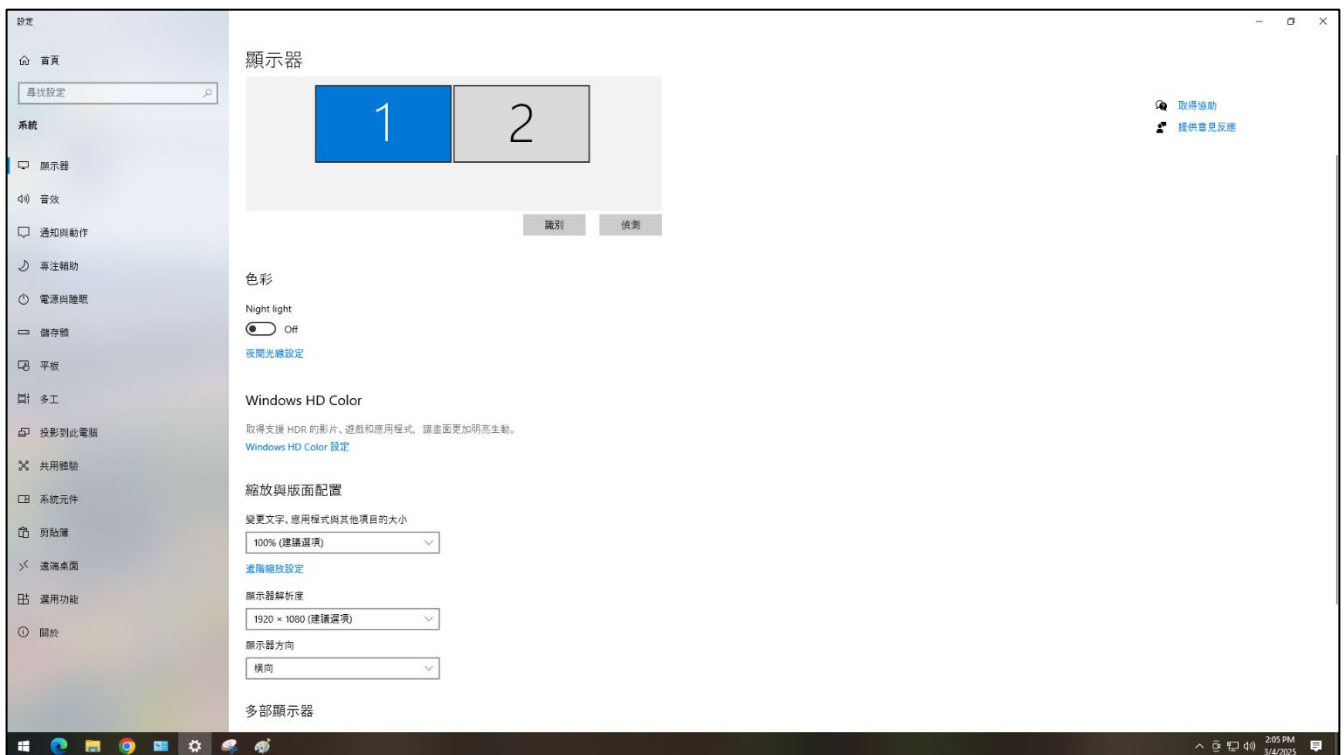
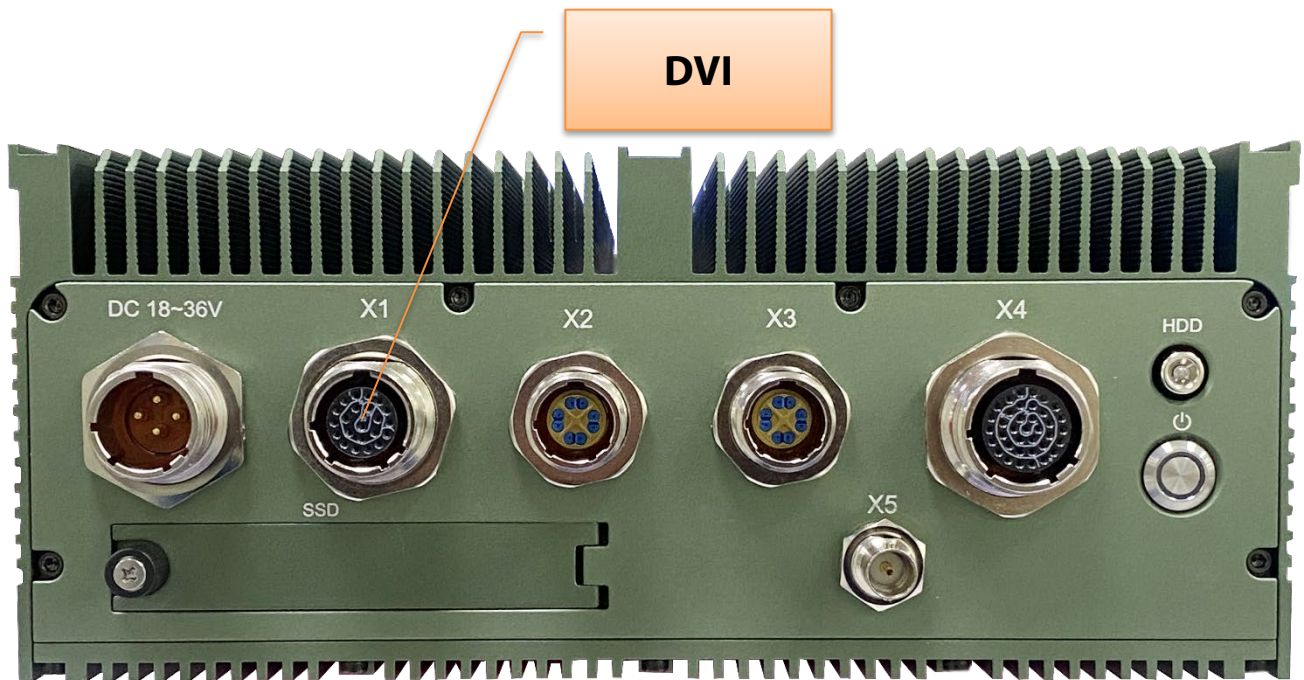
LAN Speed Test Result: Pass

LAN Data-Packet Test Result: 0 Lost (0% loss)

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5-3. DVI Port



5-4. SDI Port



-----END-----